Title: **JP06302963A2: MULTILAYER CIRCUIT BOARD AND ITS MANUFACTURE**

Derwent Title: Multilayer circuit substrate fabrication - using through hole plated substrate to achieve interlayer access with alternate insulating layers [Derwent Record]

Country: **JP** Japan
Kind: **A**

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Assignee: **TOKUYAMA SODA CO LTD**
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Abstract: PURPOSE: To form a high-density wiring pattern with highly reliable through holes by forming a first wiring pattern on the smoothed surface of a conductive layer containing the through holes.

CONSTITUTION: The circuit board uses a copper-clad glass epoxy laminated board as an insulating substrate 2 having conductive layers 1 on both surfaces and, after forming through holes 3 with a drill, plated-copper layers 4 are formed on the internal surfaces of the holes 3 and entire surface of the substrate 2 by electroplating after performing electroless plating. The layers 4 are formed by the electroless plating and electroplating after the holes 3 with the layers 4 are filled with a thermosetting solder resist as a curable insulating resin 5 and the resin 5 is hardened and the surface of the conductive layers 4 containing the curable insulating

resin is polished by successively using a No.320 and No.600 buffs. In this multilayer circuit board, therefore, a second wiring pattern 8 can be formed on a first wiring pattern 6 with an insulating layer 7 in between at a high wiring density and with high reliability.

Family: None

Forward References: **Go to Result Set:** Forward references (1)

PDF	Patent	Pub.Date	Inventor	Assignee	Title
	US6426011	2002-07-30	Katoh; Takashi	International Business Machines Corporation	Method making circuit b

Other Abstract Info: DERABS C95-017491 DERC95-017491

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